

LISTING OF CLAIMS (No amendments have been made)

1. **(Previously presented)** A polymer compound comprising:
an alkali soluble group (i), wherein
at least one hydrogen atom of a hydroxyl group in the alkali soluble group (i) is
protected by an acid dissociable, dissolution inhibiting group (ii) represented by the
general formula (1):
$$\text{---CH}_2\text{-O-R (1)}$$

(wherein R represents an organic group containing no more than 20 carbon atoms
and at least one hydrophilic group), and
wherein the polymer compound exhibits changed alkali solubility under the action
of acid.
2. **(Previously presented)** a polymer compound according to claim 1, wherein the
alkali soluble group (i) is selected from the group consisting of an alcoholic hydroxyl group, a
phenolic hydroxyl group, and a carboxyl group.
3. **(Original)** A polymer compound according to claim 2, wherein a carbon atom
adjacent to the carbon atom connected to the alcoholic hydroxyl group is bonded to at least one
fluorine atom.
4. **(Previously presented)** A polymer compound according to claim 1, wherein the
hydrophilic group is selected from the group consisting of a carbonyl group, an ester group, an
alcoholic hydroxyl group, an ether group, an imino group, and an amino group.
5. **(Original)** A photoresist composition comprising:
a base material resin component (A) which exhibits changed alkali
solubility under the action of acid; and
an acid generator component (B) which generates the acid on exposure to
radiation, wherein
the base material resin component (A) is the polymer compound according
to any one of claims 1 to 4.

6. **(Original)** A resist pattern formation method comprising:
forming a photoresist film on a substrate using the photoresist composition according to claim 5;
exposing the photoresist film; and
developing the exposed photoresist film to form a resist pattern.